

Abstract of the Disclosure:

An electronic component with at least two stacked semiconductor chips is described. The chips are respectively mounted on a wiring board. The wiring boards are stacked one
5 on top of the other and interconnected mechanically and electrically by soldered connections. The soldered connections extend through apertures in the wiring boards and over one or more levels of wiring boards stacked one on top of the other, with semiconductor chips mounted on these boards.

10 A method for producing the electronic component is also described.

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